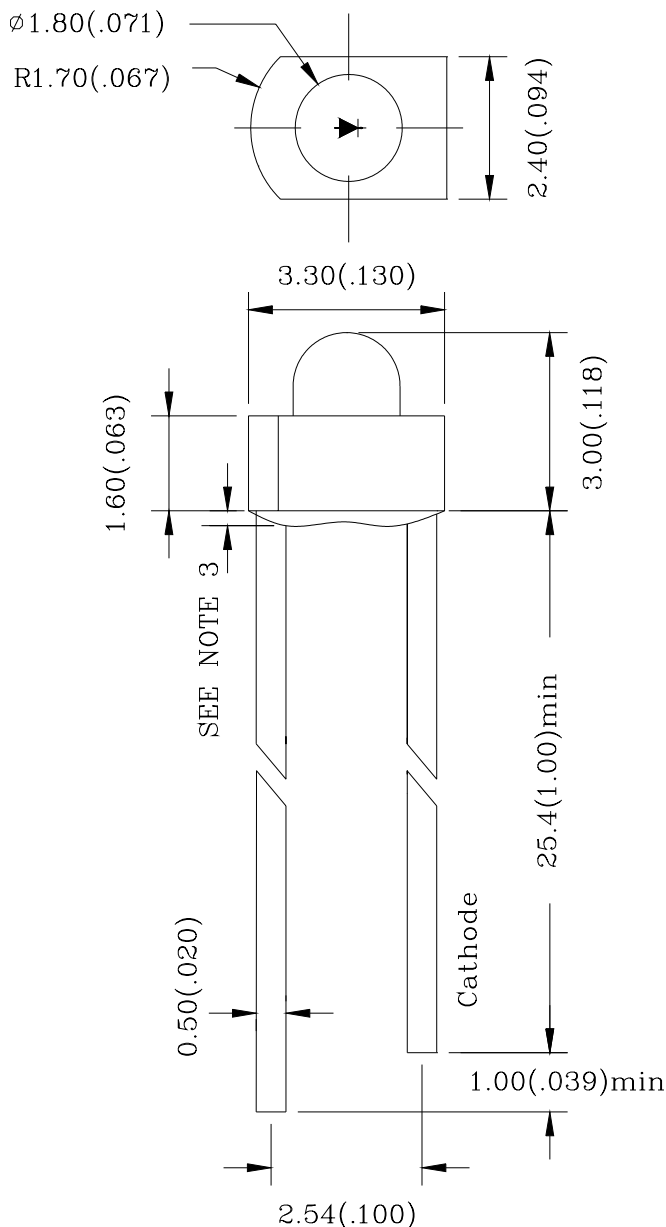


PACKAGE DIMENSIONS



Note:

- 1.All Dimensions are in millimeters.
- 2.Tolerance is $\pm 0.25\text{mm}(0.010 \text{ "})$
Unless otherwise specified.
- 3.Protruded resin under flange is $1.5\text{mm}(0.059 \text{ "})$ max.
- 4.Lead spacing is measured where the leads emerge from the package.
- 5.Specification are subject to change without notice
- 6.highlight $<-500\text{V}$ the led can withstand the max static level when assembling or operation.

FEATURES

- * 1.80mm DIA LED LAMP
- * LOW POWER CONSUMPTION
- * I.C. COMPATIBLE
- * LONG LIFE SOLID STATE RELIABILITY

CHIP MATERIALS

- * Dice Material : GaAsP/GaP
- * Light Color : ORANGE
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	ORANGE	UNIT
PAD	Power Dissipation Per Chip	60	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	20	mA
IPF	Peak Forward Current Per Chip (Duty – 0.1, 1KHz)	120	mA
—	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds			

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.2		V
IR	Reverse Current	VR = 5V			100	μA
λD	Dominant Wavelength	IF = 20mA		605		nm
Δλ	Spectral Line Half-Width	IF = 20mA		35		nm
2θ1/2	Half Intensity Angle	IF = 20mA		35		deg
IV	Luminous Intensity	IF = 20mA		2200		mcd

